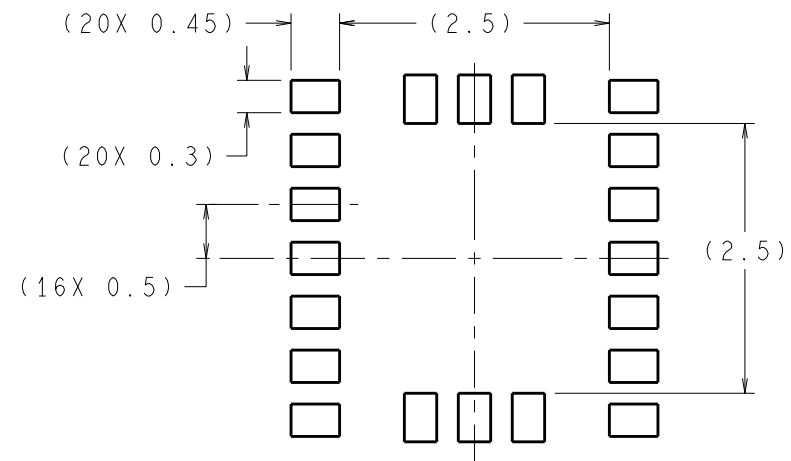
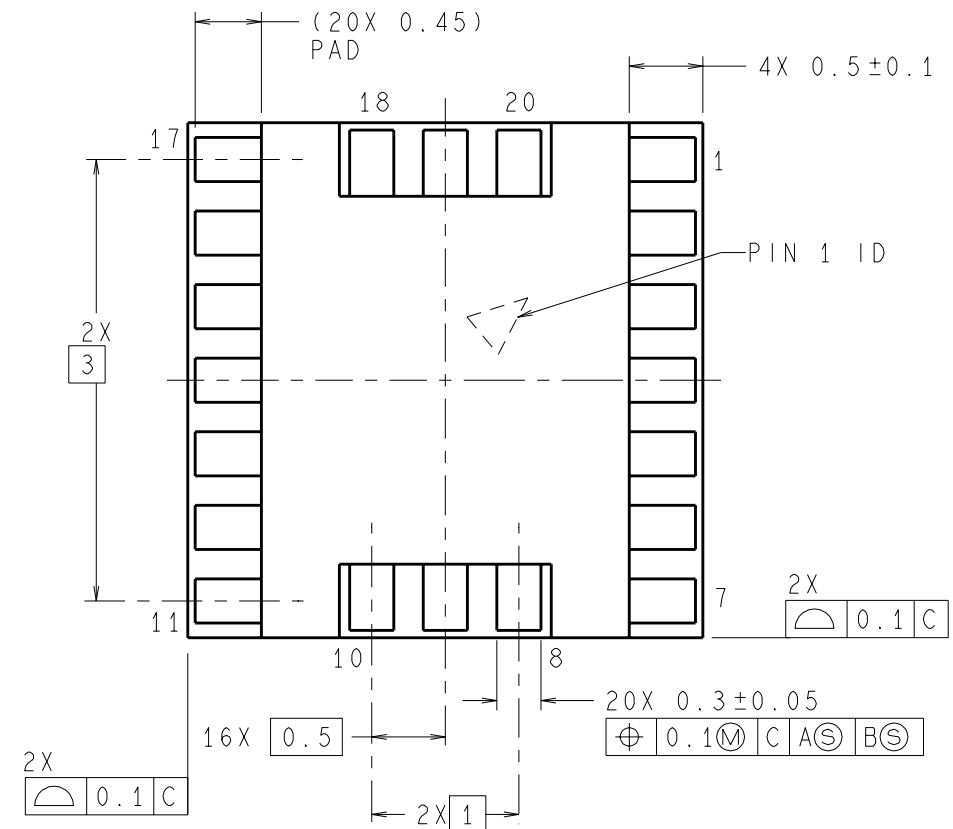
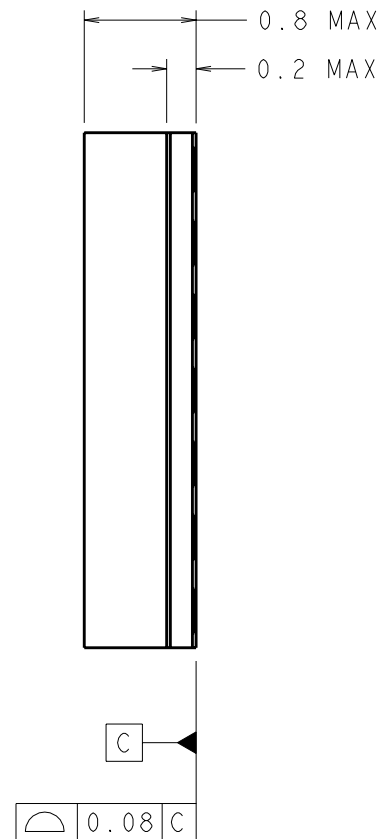
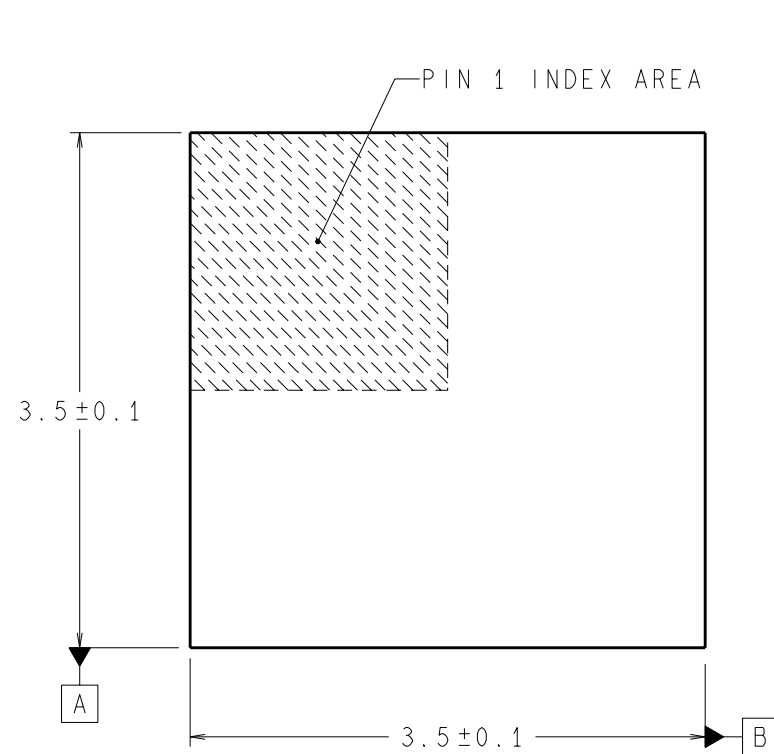


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	352	06/28/2001	TL/AT



**RECOMMENDED LAND PATTERN**  
1:1 RATIO WITH PACKAGE SOLDER PADS

**DIMENSIONS ARE IN MILLIMETERS**



NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL: BT RESIN CCL-HL832-H/S WITH TAIYO PSR4000 AUS5 SOLDER MASK.
- PLATING: Cu 15 TO 20 MICROMETERS (FULL)  
Ni 10 ± 5 MICROMETERS (LEADS ONLY)  
Au 0.75 ± 0.25 MICROMETER (LEADS ONLY)
- REFERENCE JEDEC REGISTRATION MO-208, VARIATION CCEA-1.

APPROVALS	DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN T. LEQUANG	06/28/2001				
DFTG. CHK. MARTA SUCHY	06/28/2001				
ENGR. CHK. ANNY TU	06/28/2001	<b>THIN CSP, PLASTIC, LAMINATED, 3.5 X 3.5 X 0.8 mm BODY, 20 L, 0.5 mm PITCH</b>			
PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-SLD20A	REV A
		FORMERLY: N/A		SHEET 1 of 1	